

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2018/03/15	Phebe Su

Note:

1.Material:

1.1 Housing: LCP BLACK, UL94v-0

1.2 Contact: C5191

1.3 Shell: SUS304, t=0.30mm

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding

voltage: 100 V(ac) for 1 min.

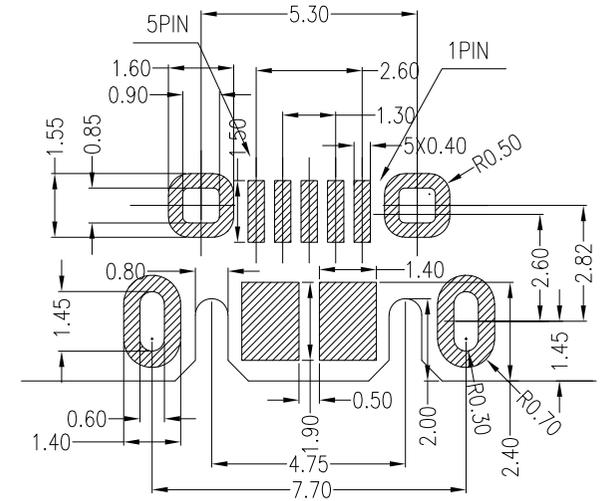
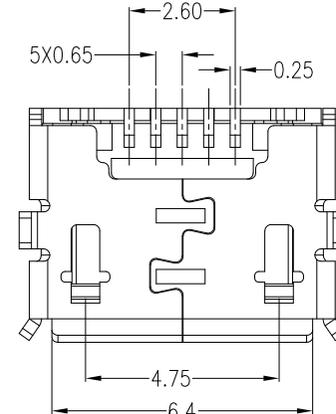
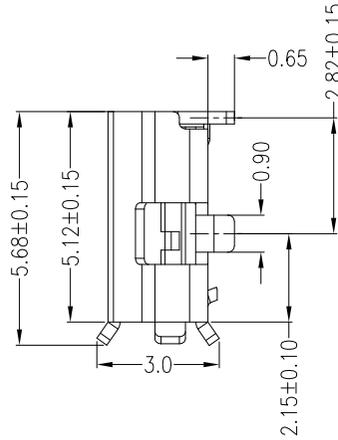
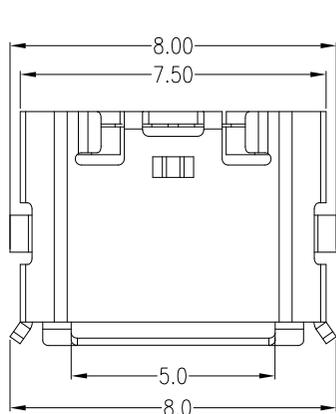
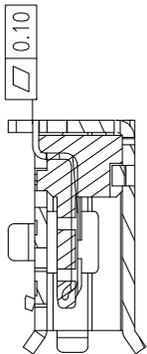
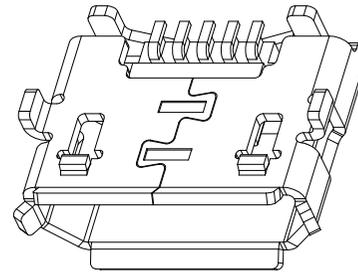
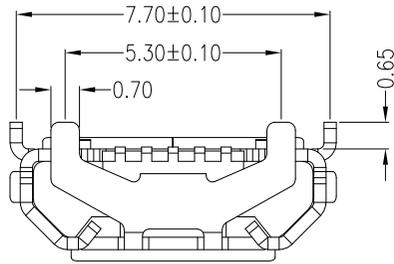
2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

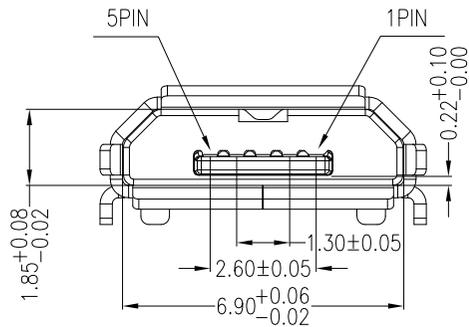
2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: -40°C~85°C



RECOMMENDED PCB LAYOUT
TOLERANCE:±0.05

▣ PAD AREA



Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.15 X:XX ±0.10 X:XXX ±0.05 ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2018/03/15	PART NAME: MICRO USB B/F SMD REVERSED	
	CHECKED BY: Janice Liu	DATE : 2018/03/15	PART NO.	MUSB05-01-349
 UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2018/03/15	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2018/03/15	DRAW NO.	SHEET NO. 1 OF 1